

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1 – 54. (Canceled)

55. (currently amended) A circuit circuitry component, used to be connected to a substrate comprising a first pad with a sidewall not covered by a solder mask, comprising:

a semiconductor device;

a metal pillar over said semiconductor device, wherein said metal pillar has a thickness of between 10 and 100 microns;

a metal layer over said metal pillar, wherein said metal layer has a bottom surface partially covered by said metal pillar and partially not covered by said metal pillar; and

a solder metal over said metal layer, wherein said solder metal is used to be bonded to said first pad.

56. (currently amended) The circuit circuitry component of Claim 55, wherein said solder metal is bonded to said first pad. ~~used to be connected to a substrate,~~

~~wherein said substrate has a pad having an edge not covered by a solder mask,~~  
~~and wherein said solder metal is bonded to said pad.~~

57. (currently amended) The circuit component ~~chip package~~ of Claim 55, wherein the distance between a sidewall ~~an edge~~ of said metal layer and a sidewall ~~an edge~~ of said metal pillar is greater than 0.2 microns.

58. (currently amended) The circuit component ~~chip package~~ of Claim 55, wherein said semiconductor device comprises a second pad and a passivation layer, said second pad exposed by an opening in said passivation layer, wherein said metal pillar is over said second pad.

59. (currently amended) The circuit component ~~chip package~~ of Claim 58 ~~55~~ further comprising a barrier layer between said metal pillar bump and said second pad.